Tentative

DMC3	866AM
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DMC366AM

Silicon NPN epitaxial planar type (Tr1)

Silicon NPN epitaxial planar type (Tr2)

For digital circuits

Marking Symbol: R6

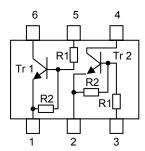
Package Code: SSSMini6-F2-B

Absolute Maximum Ratings Ta = 25 °C

Parameter (Freitter eren)		Symbol	Rating	Unit
Tr1	Collector-base voltage (Emitter open)	VCBO	50	V
Tr2	Collector-emitter voltage (Base open)	VCEO	50	V
112	Collector current	IC	80	mA
	Total power dissipation *1	PT	125	mW
Overall	Junction temperature	Tj	150	°C
	Storage temperature	Tstg	-55 to +150	°C

Note: 1. *1 Measuring on substrate at 17 mm × 10 mm × 1 mm

Internal Connection



Resistance	R1	2.2	kΩ
value	R2	47	kΩ

Pin name

1. Emitter(Tr1) 2. Emitter(Tr2)	1 111 11	an	IC .
1.	Emitter(Tr1)	4.	Collector(Tr2)
2.	Emitter(Tr2)	5.	Base(Tr1)
3.	Base(Tr2)	6.	Collector(Tr1)

Electrical Characteristics Ta = 25 °C±3 °C

Tr1,Tr2

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	VCBO	IC = 10 μA, IE = 0	50			V
Collector-emitter voltage (Base open) *1	VCEO	IC = 2 mA, IB = 0	50			V
Collector-base cutoff current (Emitter open)	ICBO	VCB = 50 V, IE = 0			0.1	μA
Collector-emitter cutoff current (Base open)	ICEO	VCE = 50 V, IB = 0			0.5	μA
Emitter-base cutoff current (Collector open)	IEBO	VEB = 6 V, IC = 0			0.2	mA
Forward current transfer ratio	hFE	VCE = 10 V, IC = 5 mA	80			-
Collector-emitter saturation voltage	VCE(sat)	IC = 10 mA, IB = 0.5 mA			0.25	V
Input voltage	Vi(on)	VCE = 0.2 V, IC = 5 mA	1.2			V
input voltage	Vi(off)	VCE = 5 V, IC = 100 μA			0.4	V
Input resistance	R1		-30%	2.2	+30%	kΩ
Resistance ratio	R1/R2		0.037	0.047	0.057	-

Note: 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors.

2. *1 Pulse measurement

Packing

Embossed type (Thermo-compression sealing) R specification: 10 000 pcs / reel

2010.3.15	2010.11.25
Prepared	Revised

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